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(54) **Title:** APPARATUS FOR DISPENSING A SOLDER WIRE

(57) **Abstract:** An apparatus is provided comprising a dispensing channel 400 for a solder wire 200, a first cooling chamber 600 for cooling the solder wire 200 with a first cooling gas 810 within the dispensing channel 400, the first cooling gas 810 being configured and arranged to pass out of a wire-facing outlet 651 away from the substrate 500, and to pass out of the dispensing outlet 650 towards the substrate 500, wherein the dispensing channel 400 for the solder wire 200 is comprised within the first cooling chamber 600.

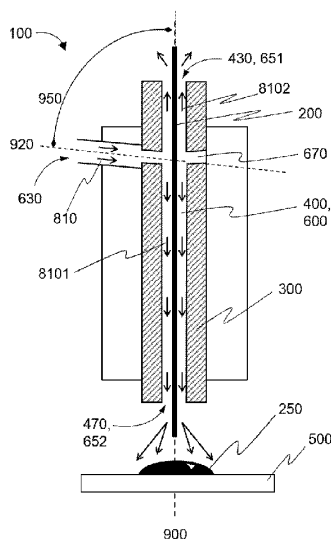


Fig. 1A

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